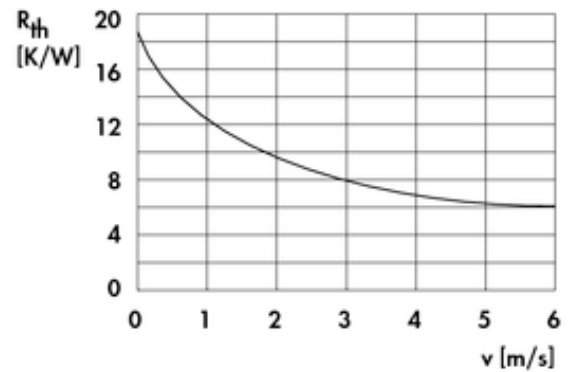
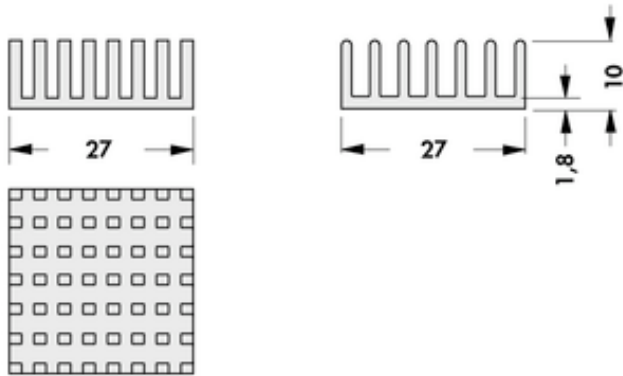
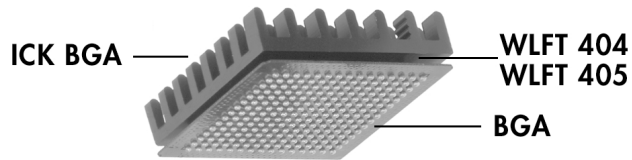


Heatsinks for BGAs / **ICK BGA 27 x 27 x 10**

27 x 27 x 10 mm, for IC design BGA and others

**Parameters of article ICK BGA 27 x 27 x 10**

<b>R<sub>th</sub> [K/W]</b>	<b>i</b> 18.5
<b>dissipation loss [W]</b>	<b>i</b> 3.3
<b>mounting method</b>	therm. conductive foil / therm. cond. adhesive
<b>socket</b>	universal
<b>suitable for processor type</b>	universal
<b>width [mm]</b>	27
<b>height [mm]</b>	10
<b>plate thickness [mm]</b>	1.8
<b>length on stock [mm]</b>	27
<b>surface treatment</b>	black anodised

**Accessories/ related articles**

Thermally conductive foil both sides adhesive / **WLFT 404 27 x 27**

Thermally conductive foil both sides adhesive / **WLFT 405 27 x 27**